



Level 6, 412 Collins Street
MELBOURNE VIC 3000
Ph (03) 9642 0655 Fax (03) 9642
5177
www.xped.com
ABN 89 122 203 196

11 May 2016

ASX Release

Telink Xped Marketing Presentation – Updated

The Company would like to provide a further updated version of the "Telink Xped Marketing Presentation".

This marketing presentation now includes a "Glossary Page" on page 24.

The Company would also like to make shareholders aware of technology an article on "Xped" that was released yesterday by "The Next Tech Stock".

This article can now be viewed on the following website link:

<http://www.nexttechstock.com/new-deal-puts-xpe-position-help-build-global-first-end-end-iot-solution/>

Xped Inquiries:

Company Secretary

T 03 9642 0655

E info@xped.com

Telink + Xped share vision on leading IoT race

WORLD LEADING, HIGHLY INTEGRATED, LOW POWER SOC
SOON WITH **ADRC TECHNOLOGY.**

ENABLING A SMARTER WORLD



Disclaimer

This presentation is not a prospectus nor an offer for securities in any jurisdiction nor a securities recommendation. The information in this presentation is an overview, is based on publicly available information and internally developed data, and does not contain all information necessary for investment decisions. In making investment decisions in connection with any acquisition of securities, investors should rely upon their own examination of the assets and consult their own legal, business and/or financial advisors and should not be relied on in connection with a decision to purchase or sell for any securities.

The information contained in this presentation has been prepared in good faith by Telink Semiconductor, and Xped Ltd. however no representation nor warranty expressed or implied is made as to the accuracy, correctness, completeness or adequacy of any statements, estimates, opinions or other information contained in this presentation.

To the maximum extent permitted by law, Telink Semiconductor and Xped Ltd their directors, officers, employees and agents disclaim liability for any loss or damage which may be suffered by any person through the use or reliance on anything contained in or omitted from this presentation.

Certain information in this presentation refers to the intentions of Telink Semiconductor but these are not intended to be forecasts, forward looking statements or statements about future matters for the purposes of the Corporations Act or any other applicable law.

The occurrence of events in the future are subject to risks, uncertainties and other factors that may impact Telink Semiconductor actual results, performance or achievements to differ from those referred to in this presentation. Accordingly, Telink Semiconductor and Xped Ltd., their directors, officers, employees and agents do not give any assurance or guarantee that the occurrence of the events referred to in this presentation will actually occur as contemplated.

About Telink

VISION: TO BECOME THE WORLD LEADING IOT CONNECTIVITY CHIP SUPPLIER

FABLESS IC DESIGN COMPANY

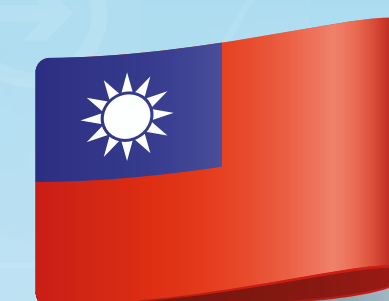
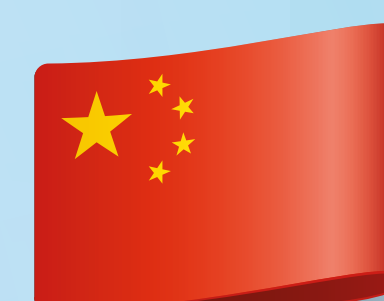
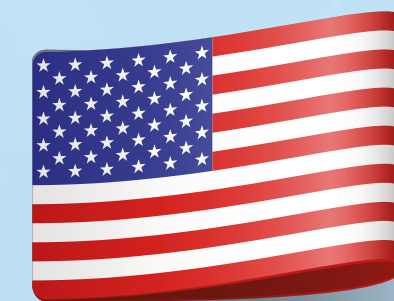
- Founded by IC design experts and executives in 2010
- Core members of technical team all from top US IC companies

FOCUS ON HIGHLY INTEGRATED RF SOC FOR IOT AND HID

- 10+ SoC in Mass Production

R&D LOCATIONS AND OFFICES

- California, USA
- Shanghai, China
- Shenzhen, China
- Taipei, Taiwan



About Xped



VISION: MAKING TECHNOLOGY HUMAN AGAIN

INTERNET OF THINGS (IOT) TECHNOLOGY BUSINESS

- Founded in 2008 by current management
- Successfully listed on ASX (April 2016)
- Working with world's largest chip manufacturers to adopt ADRC
- License agreements underway with technology partners
- Target markets include Health, Cities, Industrial, Education & Transport

INTELLECTUAL PROPERTY

- Extensive patent portfolio with over 9 patents across 14 countries.
- Continuing to innovate and expand IP including Xerts digital coupons

LOCATIONS

- Singapore
- Australia
- USA (soon)



Telink Core Competencies

THE ABILITY TO DELIVER THE HIGHEST INTEGRATION LEVEL, SMALLEST DIE SIZE AND LOWEST TOTAL BOM COST SOC PRODUCTS WITHOUT ANY COMPROMISE ON PERFORMANCE, WHICH HAS BEEN PROVEN BY MULTIPLE PRODUCTS IN MASS PRODUCTION.

Unique and pioneering chip system architecture, RF and digital block design; a systematic way to lower chip cost

Big cost advantage of our products enable us to maintain at least 20% - 30% BOM cost advantage over all major competitors

Telink-owned low cost high performance 32 bits MCU

Xped Core Competencies

EASY TO USE AND CONFIGURE WITH ONE TAP PAIRING OF ADRC DEVICES. THE ABILITY TO CONTROL AND MONITOR DEVICES, INCLUDING MONITORING USAGE AND EVENTS, WITH CAPABILITIES TO CAPTURE NECESSARY INFORMATION FOR ANALYTICS AND BIG-DATA PURPOSES. THE ARCHITECTURE IS BUILT WITH SECURITY IN MIND AND CAN BE INTEGRATED INTO COMPLEX THINGS.

Worlds first device browser (DEB) which supports Android and Apple iOS platforms



Embedded IoT stack is supplied in latest silicon from top-tier Chipset Manufacturers

RML is a new language developed by Xped; RML make devices/things self describing to smart phones; each device/thing can have more than one interface

Extensive patent portfolio IP protection granted across major jurisdictions including China and USA



IoT Problems



**THERE ARE SEVERAL COMPETING
PLATFORMS AND CONSORTIUMS**

**THERE IS NO INTEROPERABILITY
BETWEEN PLATFORMS**

**EVERY DEVICE REQUIRES A
DIFFERENT APP TO CONTROL THINGS**

**PAIRING AND CONNECTING TO
THINGS IS DIFFICULT AND THERE IS
NO STANDARD WAY OF DOING IT**

**MANUFACTURERS ARE FORCED TO
USE FIXED PROFILES FOR EACH TYPE
OF DEVICE / THING**

IoT Solutions



INTEROPERABILITY CAN ONLY BE ACHIEVED AT THE APPLICATION LAYER BY A COMMON PROTOCOL

THE WWW TAUGHT US THIS LESSON. HTTP AND HTML REVOLUTIONIZED INFORMATION INTEROPERABILITY GLOBALLY

ADRC PROVIDES RCP AND RML WHICH CAN PROVIDE GLOBAL INTEROPERABILITY BETWEEN ALL DEVICES

ADRC MAKES CONNECTING TO THINGS AS SIMPLE AS TAPPING AN NFC ENABLED SMARTPHONE TO THE THING. EVERY THING IS ADDED IN EXACTLY THE SAME WAY

ADRC PROVIDES 'DYNAMIC PROFILE' TECHNOLOGY ALLOWING MANUFACTURERS TO INNOVATE AND DIFFERENTIATE WITHOUT RESTRICTION

ADRC Features



ONE APP KNOWN AS A 'DEVICE BROWSER' CAN CONTROL EVERY DEVICE

DEVICE BROWSER, RCP AND RML ARE OPEN SOURCE TECHNOLOGIES

RML MAKES THINGS SELF DESCRIBING

EMBEDDED IOT STACK IS SUPPLIED IN POPULAR SILICON FROM TOP-TIER VENDORS INCLUDING INTEL® AND TELINK SEMICONDUCTOR

NFC ON-BOARDING OF ALL THINGS IN EXACTLY THE SAME WAY

EACH THING CAN HAVE MORE THAN ONE USER INTERFACE, E.G. (A SIMPLE ONE FOR TECHNICALLY CHALLENGED, STANDARD ONE FOR MOST AND A FULL FEATURED ONE FOR TECHNOPHILES)

THE CORE ADRC MECHANISMS ARE PROTECTED BY A SUITE OF GRANTED PATENTS

ADRC Benefits



✓ **NO CONFUSION AS TO WHICH APP TO USE TO CONTROL A DEVICE**

✓ **MANUFACTURERS CAN INNOVATE WITHOUT RESTRICTIONS**

✓ **THE EASIEST AND MOST INTUITIVE WAY TO CONNECT WITH THINGS**

✓ **THE IP CAN BE EASILY CONTROLLED AND MONETIZED**

✓ **BREAKS DOWN THE BARRIER TO ACCEPTANCE CAUSED BY PROPRIETARY TECHNOLOGIES**

✓ **USERS OF ALL ABILITIES CAN BE CATERED FOR MAKING THEIR USER EXPERIENCE AN ENJOYABLE AND MEMORABLE ONE**

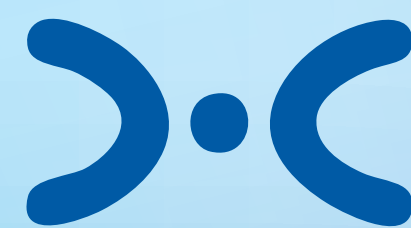
✓ **TECHNOLOGY CAN SCALE QUICKLY INTO MULTIPLE VERTICALS FOR RAPID MARKET PENETRATION**

Offering for IoT market



IEEE 802.15.4

Standardized radio technology for low power personal area networks



[Auto Discovery Remote Control]



2.4
GHz



Telink are the Leader with Significant Sustainable Competitive Advantages

WORLDS ONLY ALL-IN-ONE CHIP SUPPORTING ZIGBEE/RF4CE/BLE/BLE MESH/THREAD/HOMEKIT/ADRC (INTEGRATING NOW)

WORLDS FIRST IOT CHIP WITH ADRC

- First to market with ADRC in single IOT chip
- Simple tap and connect system for configuring devices

PROVEN BEST PERFORMANCE AND LOWEST COST BLE MESH SOLUTION

- Tier 1 companies selecting Telink's superior BLE MESH technology over competitors

MATURE AND LOWEST COST ZIGBEE/RF4CE TECHNOLOGY

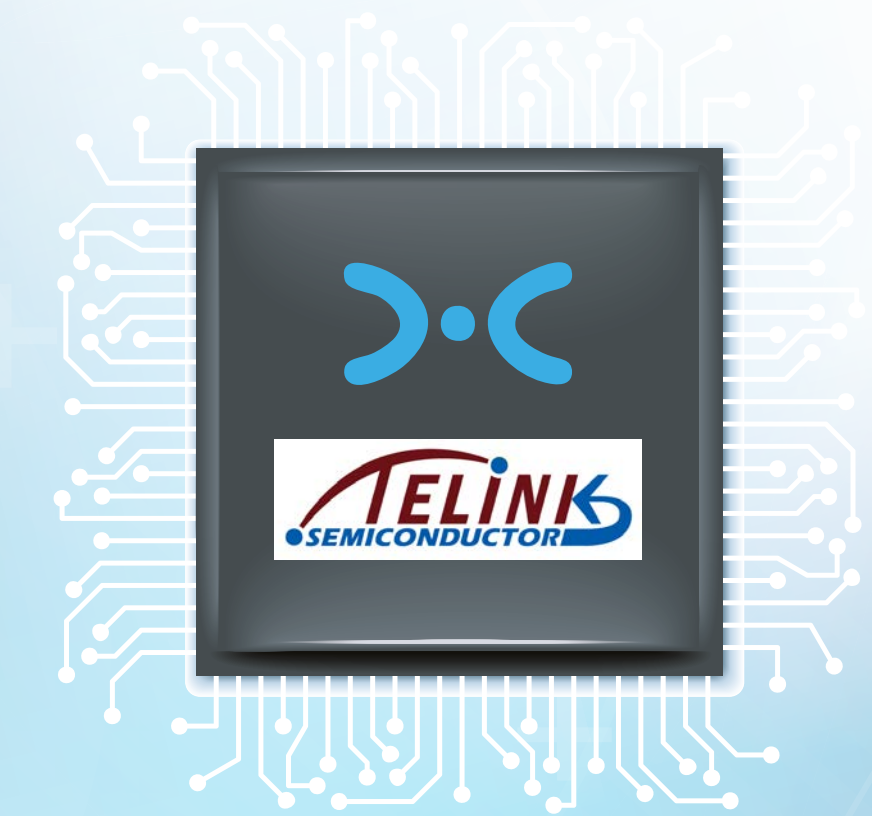
WORLDS FIRST CONCURRENT BLE + 802.15.4 DUAL MODE CHIP

- 1 year ahead of nearest competitor
- Key to IoT success: BLE talks to Smartphone, Zigbee/Thread talks to home network

HIGHEST LEVEL INTEGRATION, SMALLEST DIE SIZE & LOWEST TOTAL BOM COST

- **>30% BOM cost saving over all major competitors**

Integrating Auto Discovery Remote Control (ADRC) technology



XPED AND TELINK WILL BE FIRST TO MARKET WITH ADRC INTEGRATION ON SINGLE IOT CHIP

XPED IS WORKING WITH TWO US-LISTED CHIPSET MANUFACTURERS TO INTEGRATE ADRC INTO SPECIFIC PRODUCTS

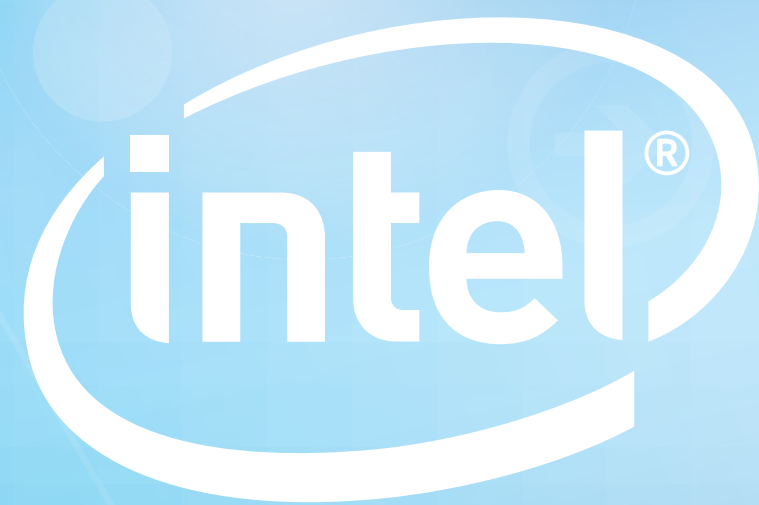
XPED HAS AN EXTENSIVE PATENT PORTFOLIO IN 14 COUNTRIES

ADRC PROVIDES AN ADVANCED TECHNOLOGY PLATFORM FOR IOT CREATING AN END-TO-END SOLUTION FOR DEVICE MANUFACTURERS AND THEIR CONSUMERS

ADRC is being integrated into Intel IoT gateway platform

INTEL CUSTOMERS WILL HAVE ACCESS TO ALL THE BENEFITS THAT ADRC TECHNOLOGY PROVIDES, INCLUDING NFC ON-BOARDING OF DEVICES WITH A SIMPLE TAP.

[HTTPS://WWW-SSL.INTEL.COM/CONTENT/WWW/US/EN/EMBEDDED/SOLUTIONS/IOT-GATEWAY/OVERVIEW.HTML](https://www-ssl.intel.com/content/www/us/en/embedded/solutions/iot-gateway/overview.html)



BLE-mesh Technology

TELINK'S PROPRIETARY BLE MESH TECHNOLOGY CAN SUPPORT MULTIPLE TERMINALS TO CONTROL MULTIPLE SMART DEVICES SIMULTANEOUSLY IN REAL TIME.

PATENTED NETWORK TRAFFIC CONTROL TECHNOLOGY TO ENSURE REAL TIME STATUS AND CONSISTENT CONTROL.

HARDWARE TECHNOLOGY SUPPORTS APPLE HOMEKIT.



MESH NETWORKING WILL BECOME AN INTEGRAL COMPONENT IN ENSURING CONSUMERS' BLUETOOTH ENABLED:

- Smart locks
- Lights
- HVAC (heating, ventilation and air-conditioning) systems
- Appliances work together to deliver a seamless smart home experience

BLE-mesh Technology

TELINK'S BLE MESH TECHNOLOGY PROVIDES THE OPTIMUM PRODUCT USER EXPERIENCE BECAUSE OF THE UNIQUE FEATURES IT IS ABLE TO SUPPORT AND NOW WITH XPED AND TELINK COLLABORATION TO INTEGRATE ADRC TECHNOLOGY WILL BECOME A DOMINATING FORCE IN THE IOT MARKET.

For smart lighting developers, Telink provides a software development kit that delivers turnkey hardware reference designs.

This includes reference hardware and firmware, light module schematic and PCB (with interface to all types of LED drivers), remote control schematic and PCB, ZigBee/BLE/2.4Ghz stack, profiles, and UI's (user interfaces), and free Android and iOS app references.

GE Lighting – Case Study

TELINK'S BLUETOOTH MESH TECHNOLOGY IS BEING USED IN CONNECTED LED LIGHT BULBS FROM GE LIGHTING, IN ITS C BY GE PRODUCT FAMILY.

THE WIRELESS CONNECTED LIGHTING SOLUTION PROVIDED BY TELINK ENABLES CUSTOMERS TO EASILY IMPLEMENT FEATURES LIKE:

- On/off control
- Dimming and colour space
- Grouping control
- Scene mode control
- Timer or sensor integration
- Control bridge
- Mesh networks
- Power consumption profiling



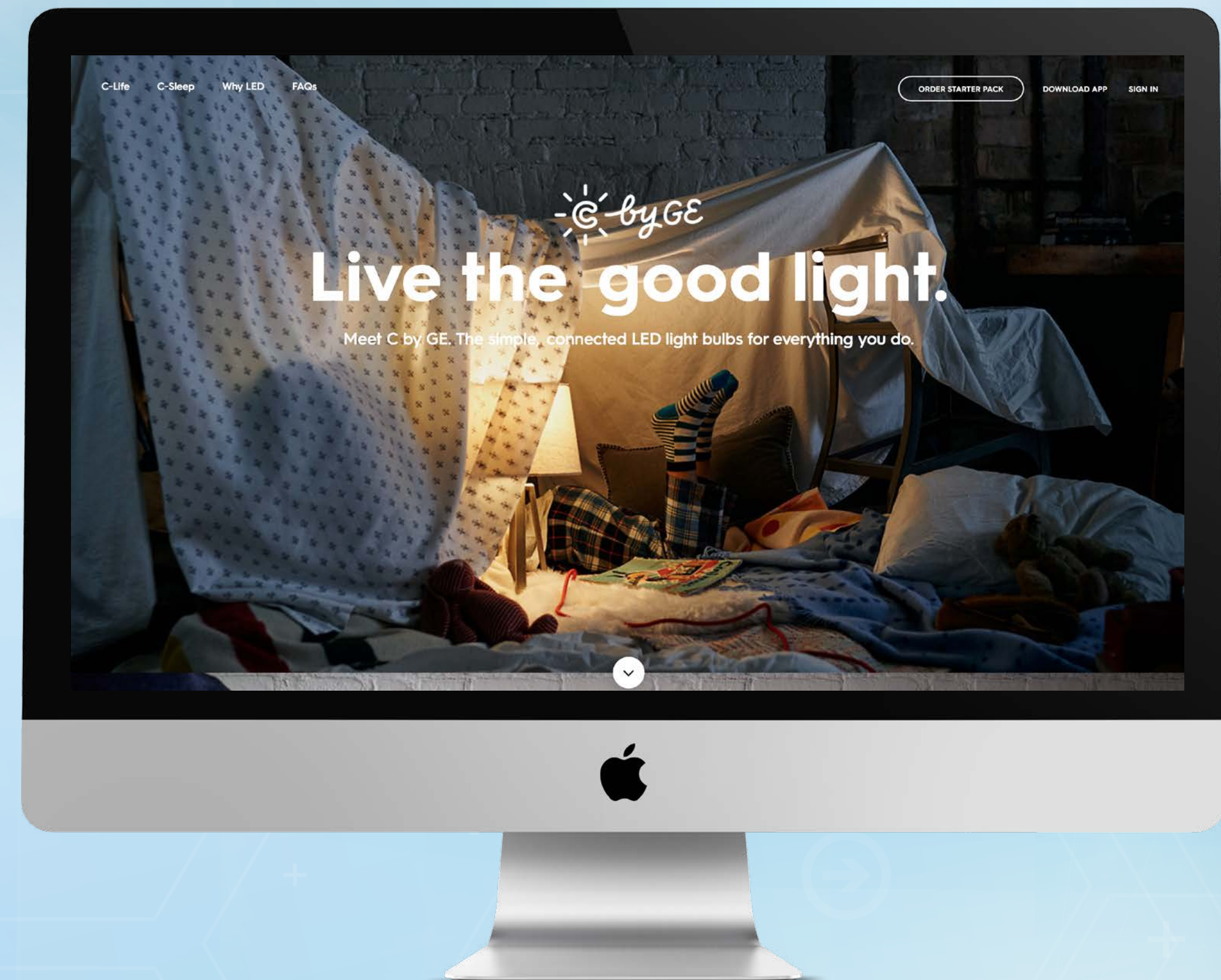
GE Lighting – Case Study

“For many, lighting is the gateway to a smart home that connects other devices including smart thermostats, security cameras and smoke alarms. While interoperability is key, in a crowded market with no clear platform winner, we wanted to give consumers the option for a standalone smart lighting solution”.

Tom Stimac, Chief Innovation Manager, GE Lighting



[WWW.CBYGE.COM](http://www.cbyge.com)

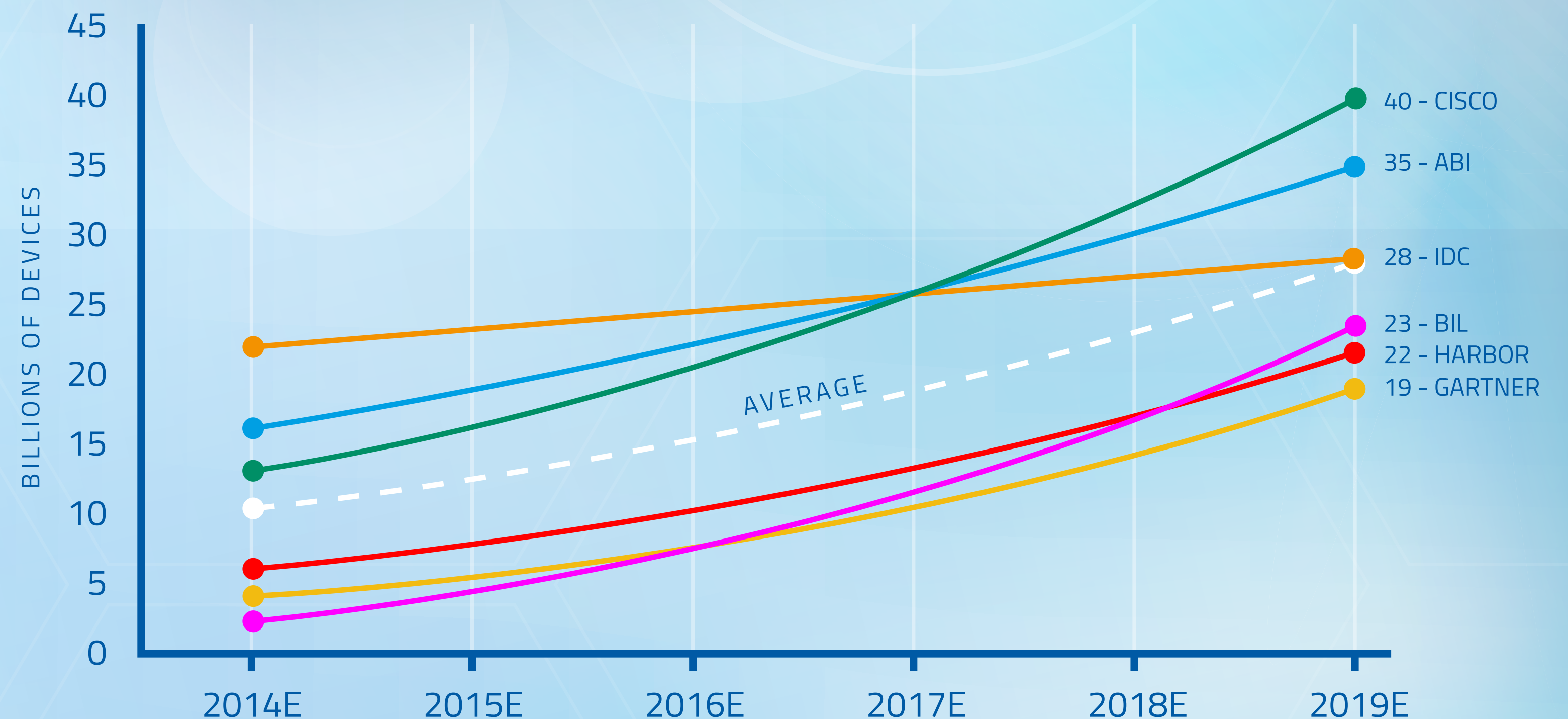


SOURCE: [HTTP://WWW.LEDSMAGAZINE.COM/UGC/2016/03/30/TELINK-SEMICONDUCTOR-ENABLES-GE-CONNECTED-LIGHTING-USING-ADVANCED-BLUETOOTH-LOW-ENERGY-MESH-TECHNOLOGY.HTML](http://WWW.LEDSMAGAZINE.COM/UGC/2016/03/30/TELINK-SEMICONDUCTOR-ENABLES-GE-CONNECTED-LIGHTING-USING-ADVANCED-BLUETOOTH-LOW-ENERGY-MESH-TECHNOLOGY.HTML)

IoT Market – Huge Growth Forecast

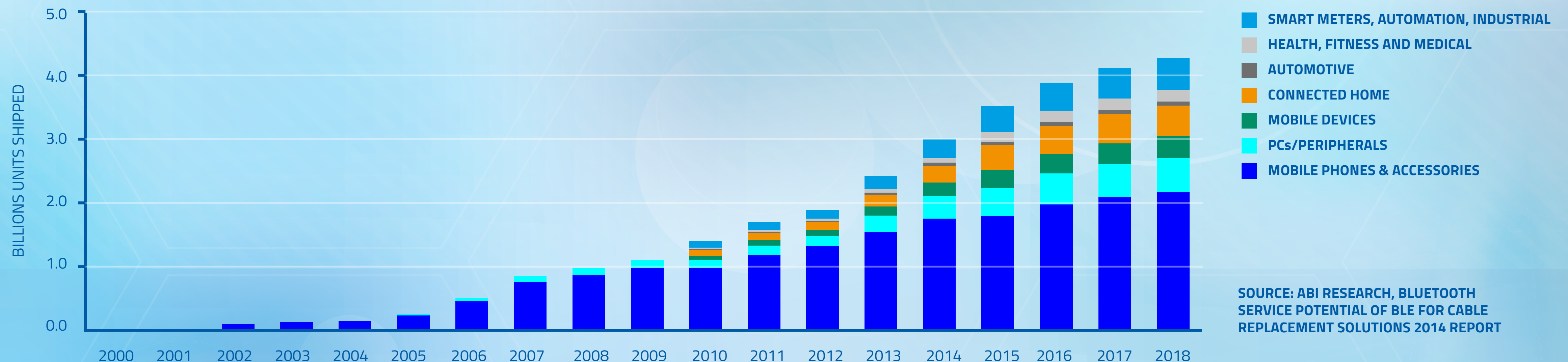
**THE IOT CONNECTED
DEVICES WILL REACH
20 - 40 BILLION
UNITS BY 2019. THE
MARKET SIZE FOR IOT
CONNECTIVITY CHIP IS
GOING TO BE HUGE!**

SOURCE: JOHN GREENOUGH, "THE INTERNET OF THINGS
IS RISING: HOW THE IOT MARKET WILL GROW ACROSS
SECTORS," BUSINESS INSIDER INTELLIGENCE, OCTOBER 8,
2014. PRODUCED BY ADAM THIERER AND ANDREA CASTILLO,
MERCATUS CENTRE AT GEORGE MASON UNIVERSITY, 2015.



BLE Market

BLUETOOTH ENABLED DEVICE ANNUAL SHIPMENTS, MAJOR MARKETS WORLD MARKET, FORECAST: 2000 TO 2018



According to a report by **ABI Research** titled, "Emerging Bluetooth Verticals," cumulative shipments of BLE-enabled devices are forecast to exceed 4 billion devices by 2017. ABI also estimates that in 2012 there was an installed base of 3.6 billion Bluetooth-enabled devices. By 2018 this is forecast to grow to almost 10 billion.

1.8 billion LED bulbs were sold in 2014, 45.1% CAGR till 2019. According to **On World** by 2020, there will be over 100 million Internet connected wireless light bulbs and lamps worldwide up from 2.4million in 2013. BLE & ZigBee are expected to be the major connectivity technologies.

Telink Customers & Revenue

SHIPPING IN EXCESS OF 6 MILLION
CHIPS PER MONTH

MORE THAN 60 VOLUME
PRODUCTION CUSTOMERS IN 2015

OVER 100 CUSTOMERS IN THE
PIPELINE INCLUDING GOOGLE NEST,
APPLE AND XIAOMI

RAPID REVENUE GROWTH. 2015
REVENUE 3X 2014 REVENUE, WITH
FORECAST 3X GROWTH FOR 2016.



Haier

FUJITSU

lenovo®

LITEON

KONKA

FOXCONN®



TOSHIBA

SHARP®

Chicony

Genius

Telink TLSR8269 chip

**WORLD'S FIRST ALL-IN-ONE SYSTEM-ON-CHIP FOR THE INTERNET OF THINGS.
THE UNIQUE SINGLE CHIP COMBINES THE FOLLOWING:**

- Radio frequency (RF)
- Digital processing
- Protocols stack software and profiles for Bluetooth Smart
- BLE Mesh
- 6LoWPAN
- Thread
- ZigBee
- RF4CE
- Apple HomeKit
- 2.4GHz proprietary standard support
- 512kB flash memory (enabling all functionality to be embedded)
- Can function up to temperature of 125C degrees, making it suitable for use in LED lighting applications.
- Supports over the over-the-air upgrades
- Product feature rollouts

**NEXT STEP IS TO
INTEGRATE XPED'S ADRC
FIRMWARE INTO THE
TELINK IOT CHIP**

Telink BLE + IEEE802.15.4 + ADRC Multi-Standard Wireless SoC

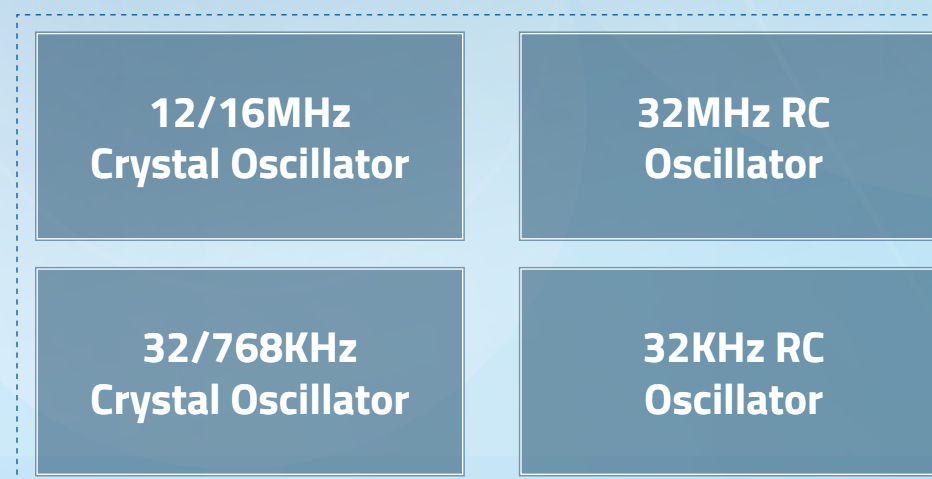
TARGET APPLICATIONS:

- Smartphone and tablet accessories
- RF Remote Control
- Sports and fitness tracking
- Wearable devices
- Wireless toys
- Building Automation
- Intelligent Logistics/Transportation/City
- Industrial Control
- Smart Lighting, Smart Home devices
- Smart Grid
- Consumer Electronics
- Health Care
- **Low-energy Wi-Fi coming soon!**

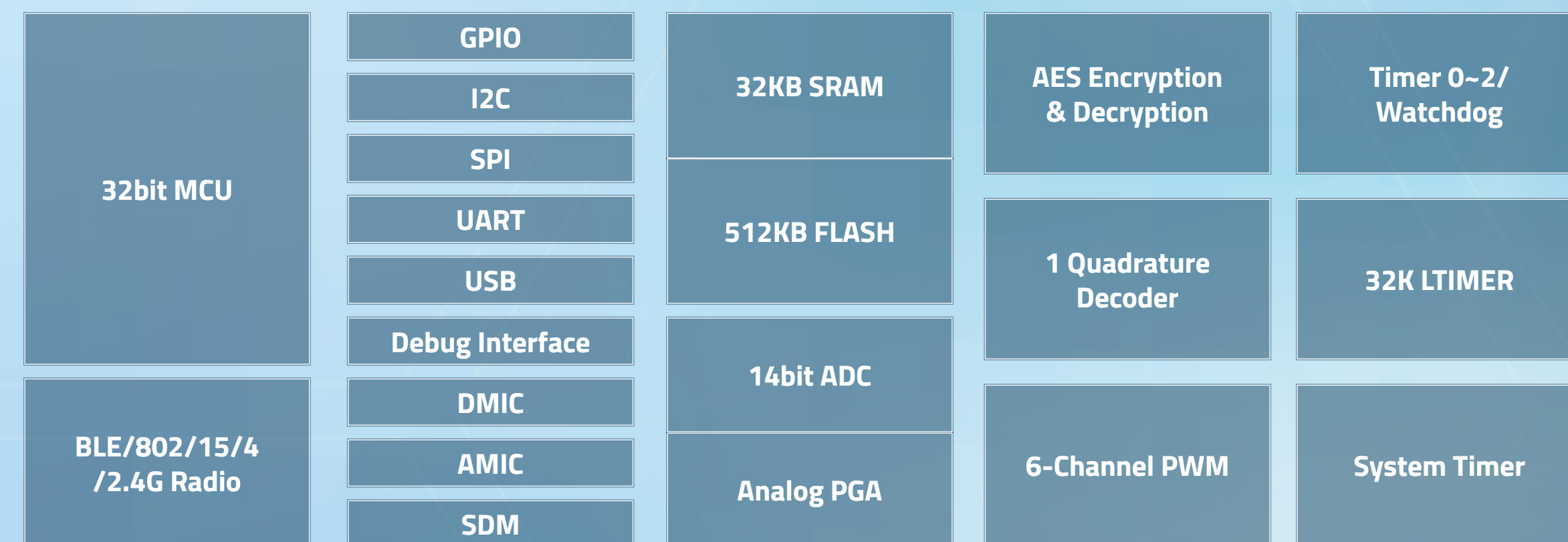


[Auto Discovery Remote Control]

CLOCK



POWER MANAGEMENT



INTERFACE

Glossary

ADRC	Auto Discovery Remote Control	IOT	Internet of Things	RML	Resource Modelling Language
AMIC	AMIC Technology Chip Manufacturer	IP	Intellectual Property	SDM	Solenoid Driver Module
ASX	Australian Stock Exchange	LDO	Low Dropout Regulator	SOC	System On a Chip
BLE	Bluetooth Low Energy	LED	Light Emitting Diode	UART	User Asynchronous Receiver/Transmitter
BOM	Bill of Materials	MCU	Media Control Unit	UI	User Interface
CAGR	Compound Annual Growth Rate	NFC	Near Field Communication	USB	Universal Serial Bus
DEB	Device Browser	PCB	Printed Circuit Board	XML	Extensible Markup Language
GPIO	Generic Pin on an Integrated Circuit	PGA	Programmable Gain Amplifier	ZIGBEE	Low data rate, two-way standard for home automation and data networks
HID	High intensity discharge	PWM	Pulse Width Modulation		
IC	Integrated Circuit	RCP	Resource Control Protocol		
I2C	Inter-Integrated Circuited	RF	Radio Frequency		
		RF4CE	Radio Frequency for Consumer Electronics		

Thank you for your time.

FOR MORE INFORMATION VISIT WWW.XPED.COM
OR EMAIL INFO@XPED.COM